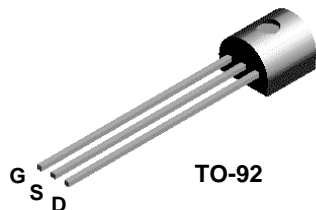
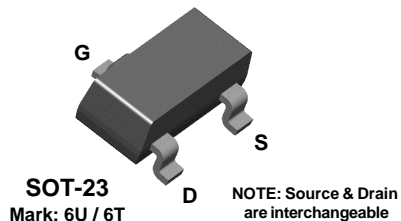


J309
J310



MMBFJ309
MMBFJ310



J309 / J310 / MMBFJ309 / MMBFJ310

N-Channel RF Amplifier

This device is designed for VHF/UHF amplifier, oscillator and mixer applications. As a common gate amplifier, 16 dB at 100 MHz and 12 dB at 450 MHz can be realized. Sourced from Process 92.

Absolute Maximum Ratings*

TA = 25°C unless otherwise noted

| Symbol | Parameter | Value | Units |
|-----------------------------------|--|-------------|-------|
| V _{DS} | Drain-Source Voltage | 25 | V |
| V _{GS} | Gate-Source Voltage | - 25 | V |
| I _{GF} | Forward Gate Current | 10 | mA |
| T _J , T _{stg} | Operating and Storage Junction Temperature Range | -55 to +150 | °C |

*These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

NOTES:

- 1) These ratings are based on a maximum junction temperature of 150 degrees C.
- 2) These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

Thermal Characteristics

TA = 25°C unless otherwise noted

| Symbol | Characteristic | Max | | Units |
|------------------|---|-----------|---------------|-------|
| | | J309-J310 | *MMBFJ309-310 | |
| P _D | Total Device Dissipation | 625 | 350 | mW |
| | Derate above 25°C | 5.0 | 2.8 | mW/°C |
| R _{θJC} | Thermal Resistance, Junction to Case | 125 | | °C/W |
| R _{θJA} | Thermal Resistance, Junction to Ambient | 357 | 556 | °C/W |

* Device mounted on FR-4 PCB 1.6" X 1.6" X 0.06."

N-Channel RF Amplifier

(continued)

Electrical Characteristics

TA = 25°C unless otherwise noted

| Symbol | Parameter | Test Conditions | Min | Typ | Max | Units |
|--------|-----------|-----------------|-----|-----|-----|-------|
|--------|-----------|-----------------|-----|-----|-----|-------|

OFF CHARACTERISTICS

| | | | | | | |
|----------------------|-------------------------------|--|----------------|--|----------------|----------|
| V _{(BR)GSS} | Gate-Source Breakdown Voltage | I _G = - 1.0 μA, V _{DS} = 0 | - 25 | | | V |
| I _{GSS} | Gate Reverse Current | V _{GS} = - 15 V, V _{DS} = 0 V _{GS} = - 15 V, V _{DS} = 0, T _A = 125°C | | | - 1.0 - 1.0 | nA μA |
| V _{GS(off)} | Gate-Source Cutoff Voltage | V _{DS} = 10 V, I _D = 1.0 mA | - 1.0 - 2.0 | | - 4.0 - 6.5 | V V |

ON CHARACTERISTICS

| | | | | | | |
|--------------------|----------------------------------|--|------------|----------|----------|----------|
| I _{DSS} | Zero-Gate Voltage Drain Current* | V _{DS} = 10 V, V _{GS} = 0 | 309 310 | 12 24 | 30 60 | mA mA |
| V _{GS(f)} | Gate-Source Forward Voltage | V _{DS} = 0, I _G = 1.0 mA | | | 1.0 | V |

SMALL SIGNAL CHARACTERISTICS

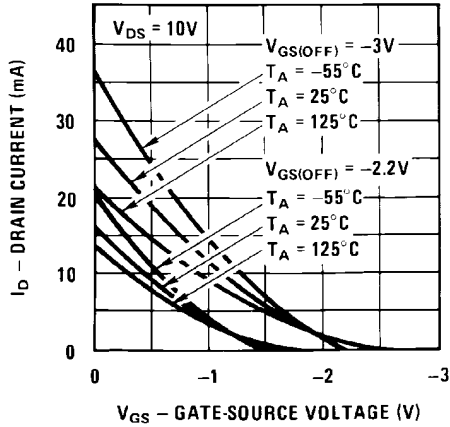
| | | | | | | |
|----------------------|--|--|------------|------------------|------------------|----------------|
| Re(Y _{is}) | Common-Source Input Conductance | V _{DS} = 10, I _D = 10 mA, f = 100 MHz | 309 310 | 0.7 0.5 | | mmhos mmhos |
| Re(Y _{os}) | Common-Source Output Conductance | V _{DS} = 10, I _D = 10 mA, f = 100 MHz | | 0.25 | | mmhos |
| G _{pg} | Common-Gate Power Gain | V _{DS} = 10, I _D = 10 mA, f = 100 MHz | | 16 | | dB |
| Re(Y _{fs}) | Common-Source Forward Transconductance | V _{DS} = 10, I _D = 10 mA, f = 100 MHz | | 12 | | mmhos |
| Re(Y _{ig}) | Common-Gate Input Conductance | V _{DS} = 10, I _D = 10 mA, f = 100 MHz | | 12 | | mmhos |
| g _{fs} | Common-Source Forward Transconductance | V _{DS} = 10, I _D = 10 mA, f = 1.0 kHz | 309 310 | 10,000 8000 | 20,000 18,000 | μmhos μmhos |
| g _{oss} | Common-Source Output Conductance | V _{DS} = 10, I _D = 10 mA, f = 1.0 kHz | | | 150 | μmhos |
| g _{fg} | Common-Gate Forward Conductance | V _{DS} = 10, I _D = 10 mA, f = 1.0 kHz | 309 310 | 13,000 12,000 | | μmhos μmhos |
| g _{og} | Common-Gate Output Conductance | V _{DS} = 10, I _D = 10 mA, f = 1.0 kHz | 309 310 | 100 150 | | μmhos μmhos |
| C _{dg} | Drain-Gate Capacitance | V _{DS} = 0, V _{GS} = - 10 V, f = 1.0 MHz | | 2.0 | 2.5 | pF |
| C _{sg} | Source-Gate Capacitance | V _{DS} = 0, V _{GS} = - 10 V, f = 1.0 MHz | | 4.1 | 5.0 | pF |
| NF | Noise Figure | V _{DS} = 10 V, I _D = 10 mA, f = 450 MHz | | 3.0 | | dB |
| e _n | Equivalent Short-Circuit Input Noise Voltage | V _{DS} = 10 V, I _D = 10 mA, f = 100 Hz | | 6.0 | | nV/√Hz |

*Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%

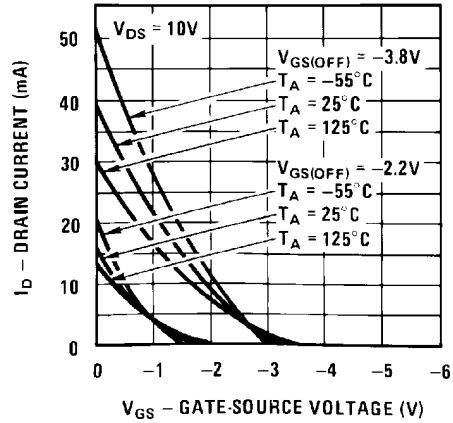
J309 / J310 / MMBFJ309 / MMBFJ310

Typical Characteristics

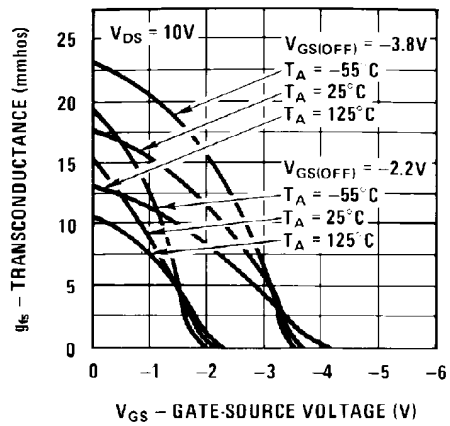
Transfer Characteristics



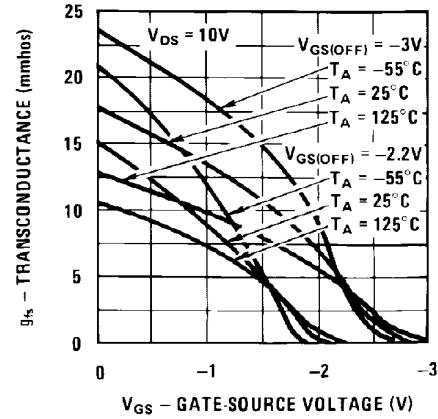
Transfer Characteristics



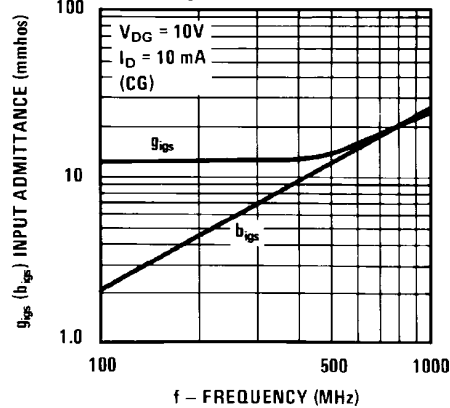
Transfer Characteristics



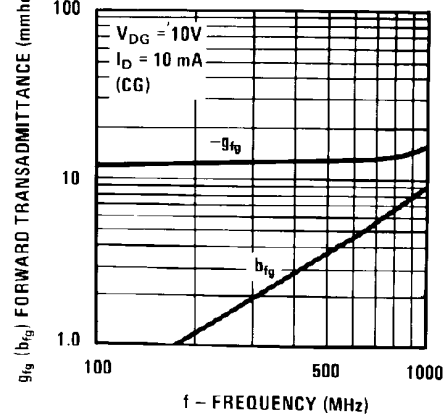
Transfer Characteristics



Input Admittance

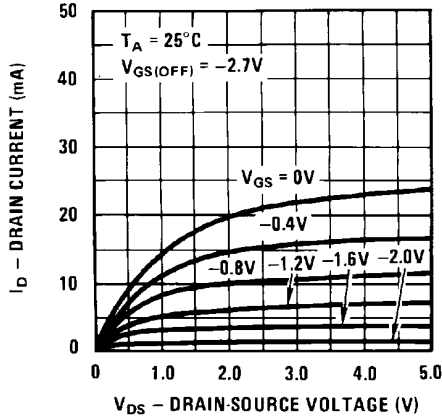


Forward Transadmittance

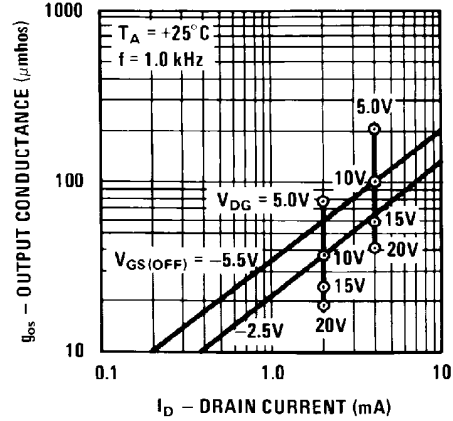


Typical Characteristics (continued)

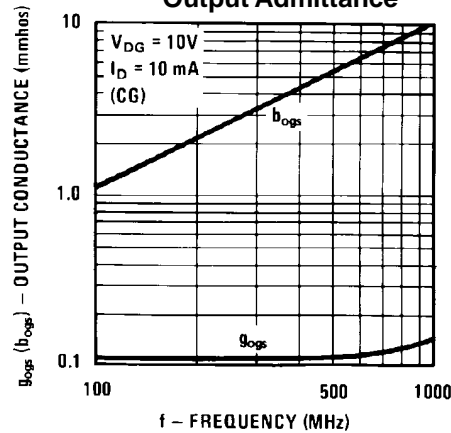
Common Drain-Source



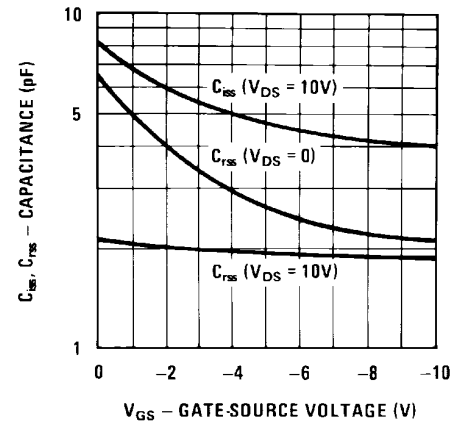
Output Conductance vs. Drain Current



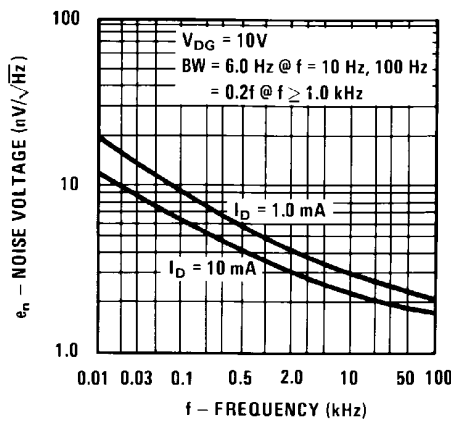
Output Admittance



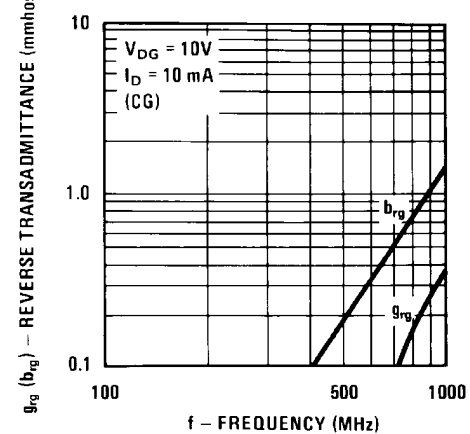
Capacitance vs. Voltage



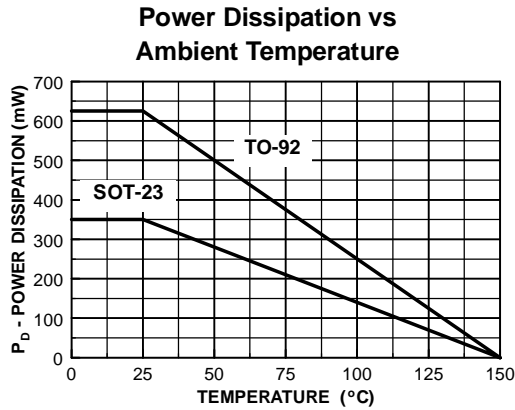
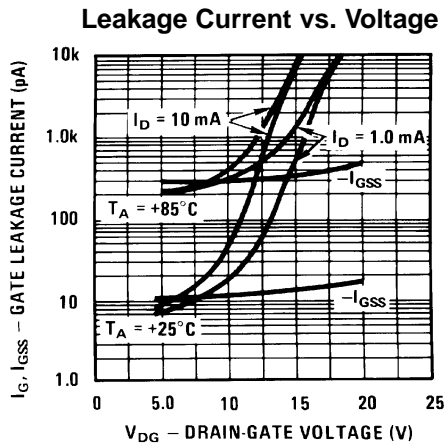
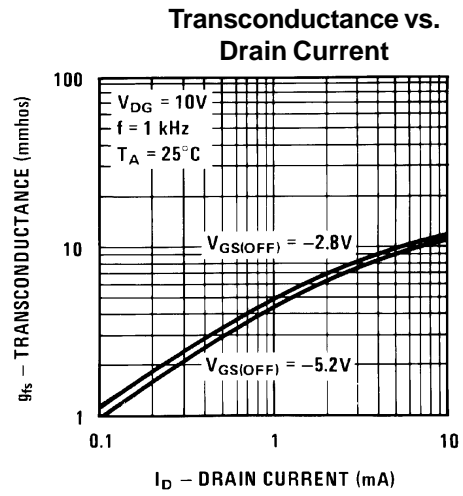
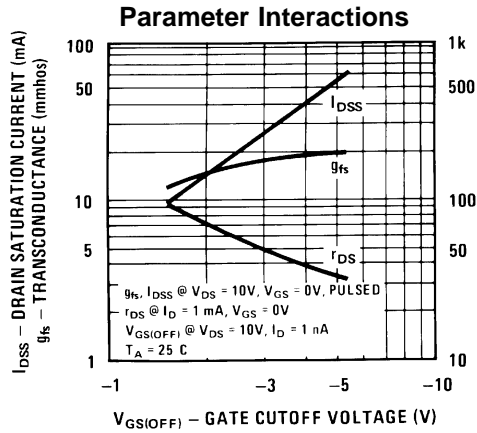
Noise Voltage vs. Frequency



Reverse Transadmittance



Typical Characteristics (continued)



TRADEMARKS

The following are registered and unregistered trademarks Fairchild Semiconductor owns or is authorized to use and is not intended to be an exhaustive list of all such trademarks.

| | | | |
|-----------------------------------|----------------------------------|----------------------------------|-------------------------|
| ACE ^x TM | FAST ^r TM | PowerTrench [®] | SyncFET TM |
| Bottomless TM | GlobalOptoisolator TM | QFET TM | TinyLogic TM |
| CoolFET TM | GTO TM | QS TM | UHC TM |
| CROSSVOLT TM | HiSeC TM | QT Optoelectronics TM | VCX TM |
| DOME TM | ISOPLANAR TM | Quiet Series TM | |
| E ² CMOS TM | MICROWIRE TM | SILENT SWITCHER [®] | |
| EnSigna TM | OPTOLOGIC TM | SMART START TM | |
| FACT TM | OPTOPLANAR TM | SuperSOT TM -3 | |
| FACT Quiet Series TM | PACMAN TM | SuperSOT TM -6 | |
| FAST [®] | POP TM | SuperSOT TM -8 | |

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION. As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, or (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in significant injury to the user.
2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

PRODUCT STATUS DEFINITIONS

Definition of Terms

| Datasheet Identification | Product Status | Definition |
|--------------------------|------------------------|---|
| Advance Information | Formative or In Design | This datasheet contains the design specifications for product development. Specifications may change in any manner without notice. |
| Preliminary | First Production | This datasheet contains preliminary data, and supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design. |
| No Identification Needed | Full Production | This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design. |
| Obsolete | Not In Production | This datasheet contains specifications on a product that has been discontinued by Fairchild semiconductor. The datasheet is printed for reference information only. |